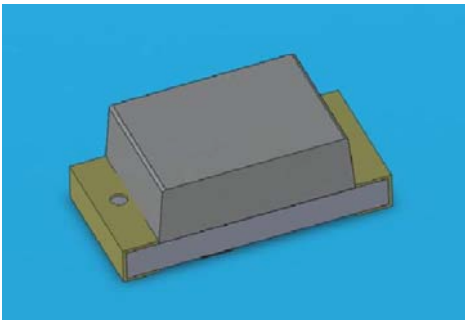


SMD ■ B

19-113-BHC-A0P1Q1K0E-3T-AM

**Features**

- RoHS compliant
- Chip LED package.
- Colorless clear resin.
- Wide viewing angle 120°
- Brightness:45 to 90 mcd at 20 mA.
- Qualification according to AEC-Q101.
- Precondition: Bases on JEDEC J-STD 020 Level 3.
- Automotive reflow profile (IR reflow or wave soldering)

Applications

- Automotive backlighting or indicator: Dashboard, switch, audio and video equipments...etc.
- Backlight: LCD, switches, symbol, mobile phone and illuminated advertising.
- Display for indoor and outdoor application.
- Ideal for coupling into light guides.
- Substitution of traditional light.
- Optical indicator.
- General applications.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Blue	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Forward Current	I _F	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA
Power Dissipation	P _d	95	mW
Junction Temperature	T _j	125	°C
Operating Temperature	T _{opr}	-40 ~ +100	°C
Storage Temperature	T _{stg}	-40 ~ +110	°C
Thermal Resistance	R _{th J-A}	800	K/W
	R _{th J-S}	450	K/W
ESD (Classification acc. AEC Q101)	ESD _{HBM}	2000	V
	ESD _{MM}	200	V
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	45	-----	90	mcd	IF=20mA
Viewing Angle	2θ _{1/2}	-----	120	-----	deg	
Peak Wavelength	λp	-----	468	-----	nm	
Dominant Wavelength	λd	464.5	----	476.5	nm	
Spectrum Radiation Bandwidth	Δλ	-----	25	-----	nm	
Forward Voltage	V _F	2.70	----	3.30	V	IF=20mA
Temperature coefficient of λp	TC _{λp}	-----	0.06	-----	nm/K	
Temperature coefficient of λd	TC _{λd}	-----	0.4	-----	nm/K	
Temperature coefficient of V _F	TC _V	-----	-2.3	-----	mV/K	

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
P1	45	56	mcd	IF =20mA
P2	56	71		
Q1	71	90		

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

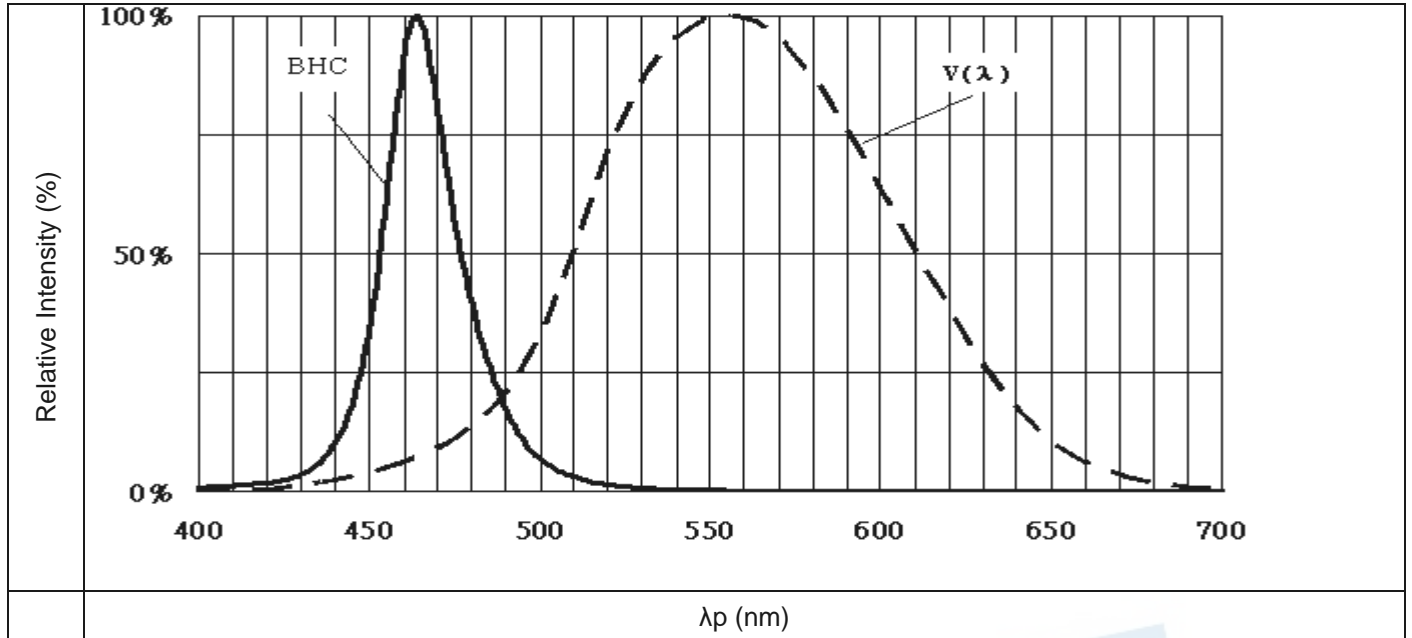
Bin Code	Min.	Max.	Unit	Condition
A9	464.5	467.5	nm	IF =20mA
A10	467.5	470.5		
A11	470.5	473.5		
A12	473.5	476.5		

Note:

Tolerance of Dominant Wavelength: ±1nm

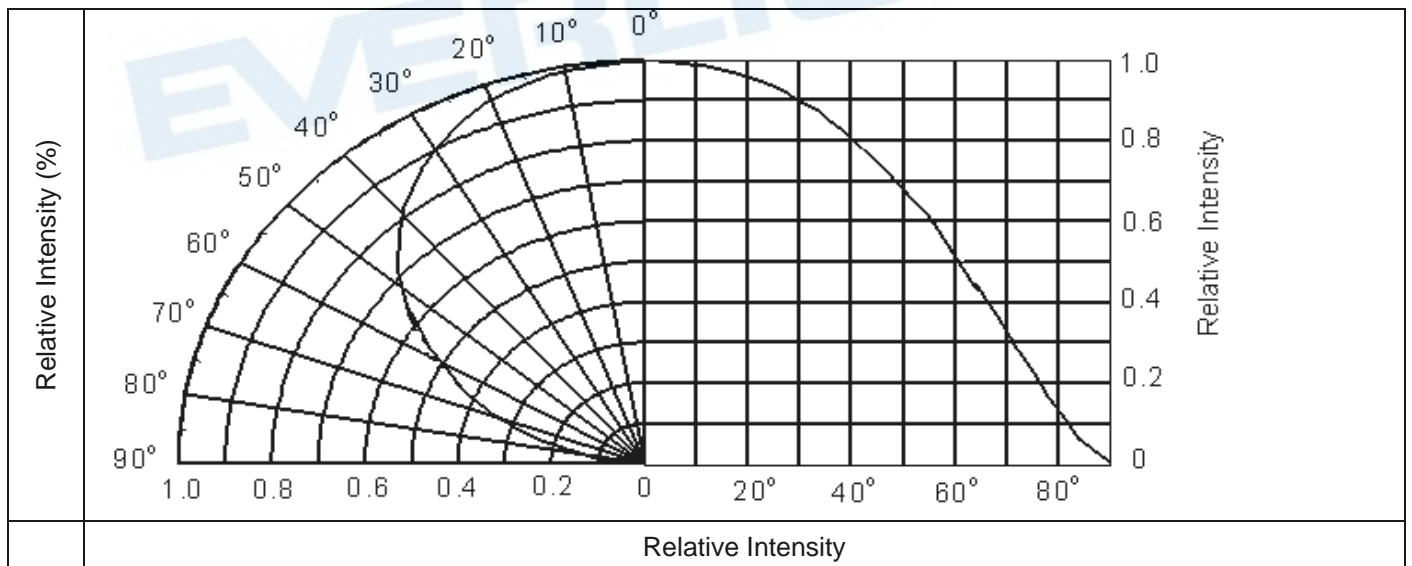
Typical Electro-Optical Characteristics Curves

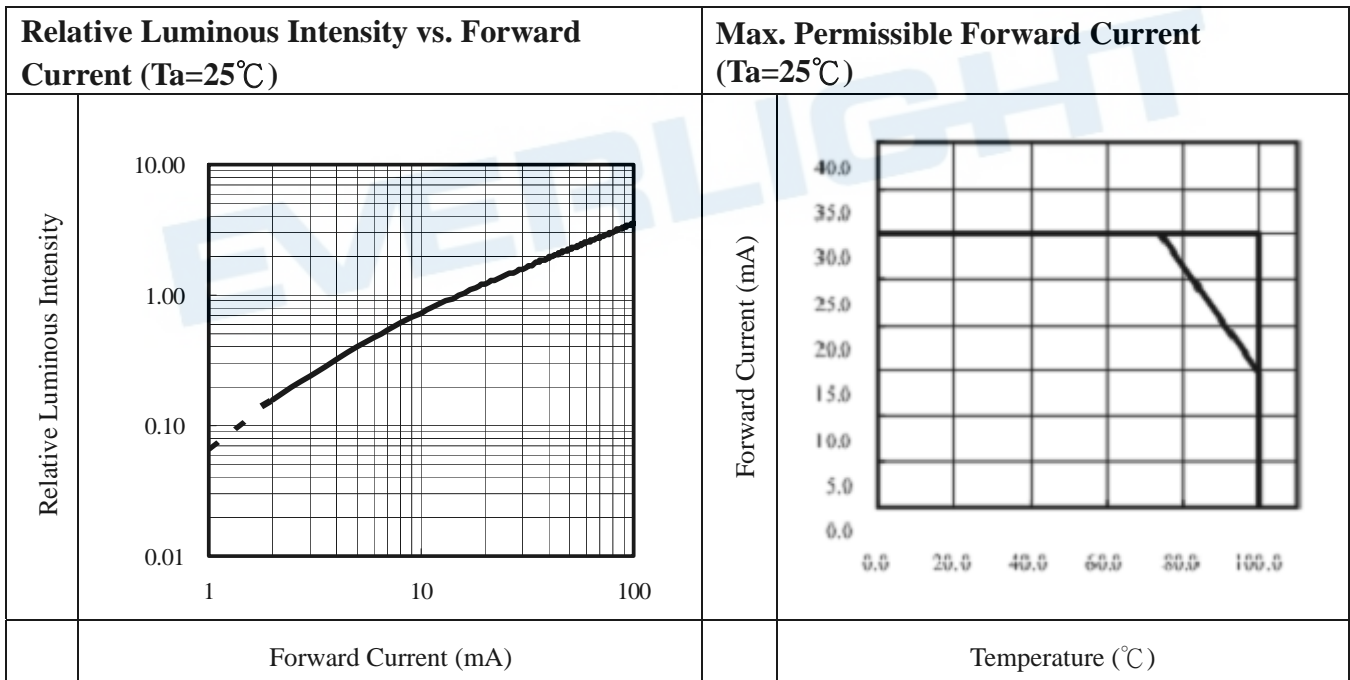
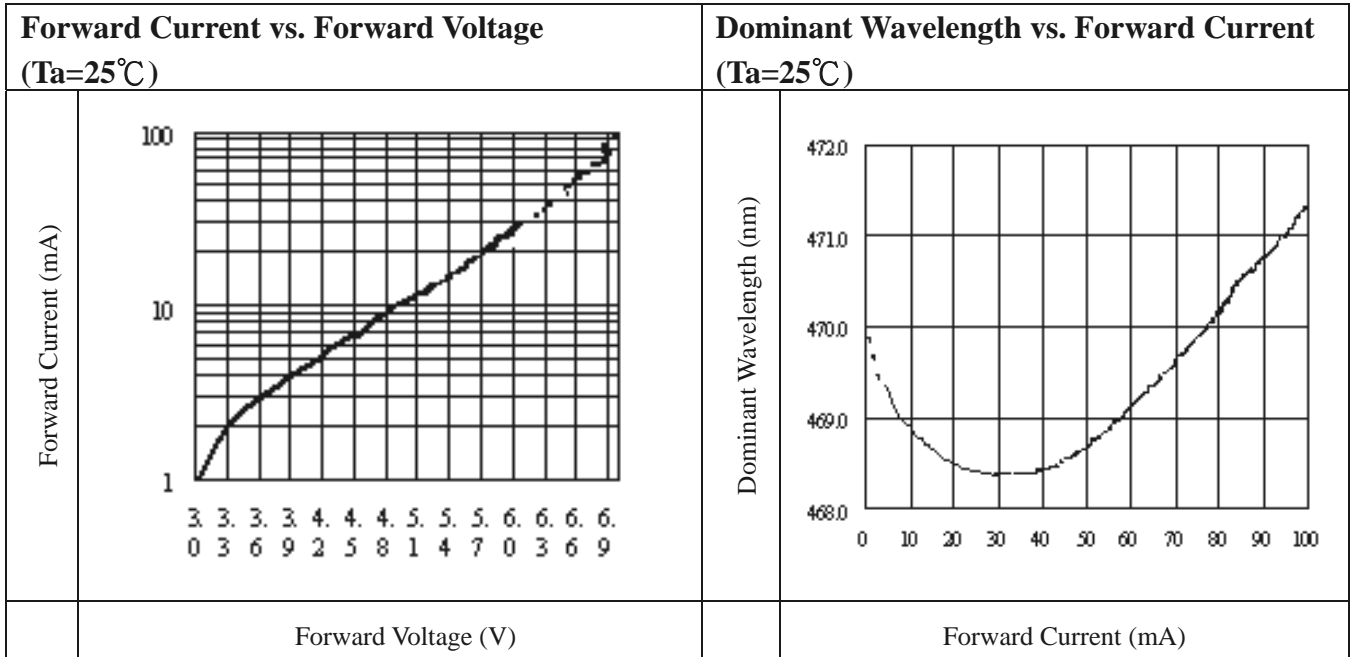
Typical Curve of Spectral Distribution



Note: V(λ)=Standard eye response curve; $I_F = 20\text{mA}$

Diagram Characteristics of Radiation

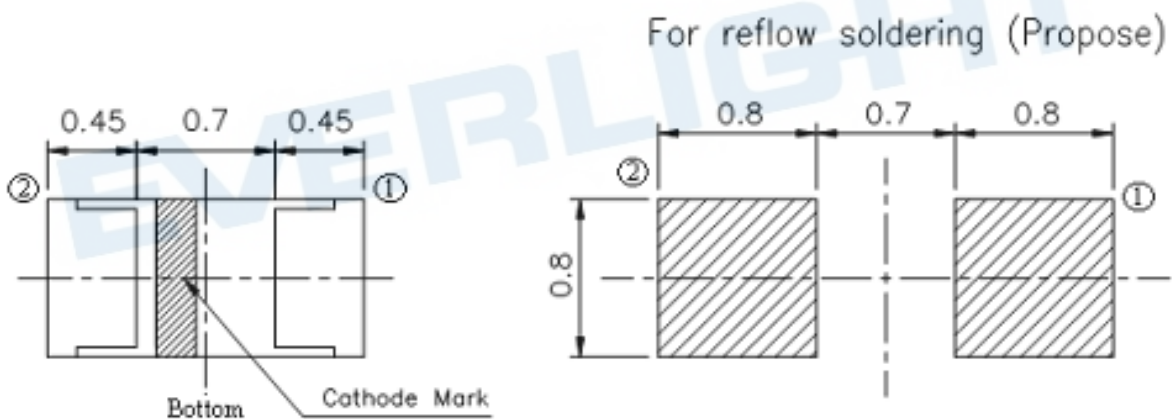
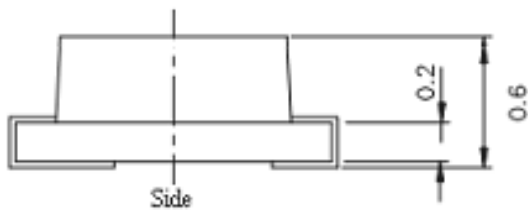
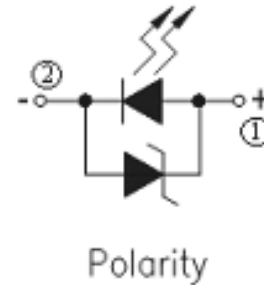
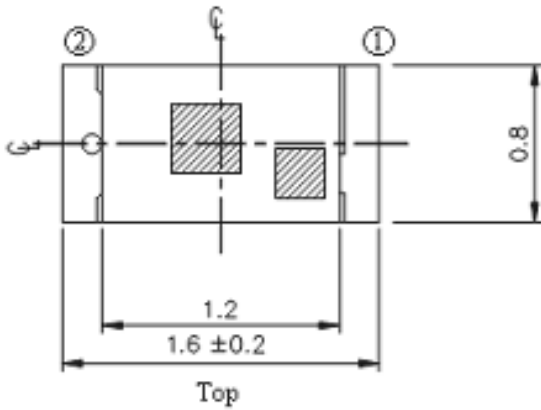




Relative Luminous Intensity vs. Junction Temperature		Relative Forward Voltage vs. Junction Temperature	
Relative Luminous Intensity		Relative Forward Voltage	
	Junction Temperature (°C)		Junction Temperature (°C)
Note: $f(T_j) = I_v / I_v(25^\circ\text{C})$; $I_F = 20\text{mA}$		Note: $\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j)$; $I_F = 20\text{mA}$	

EVERLIGHT

Package Dimension



Suggested pad dimension is just for reference only.
 Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

Moisture Resistant Packing Materials

Label Explanation

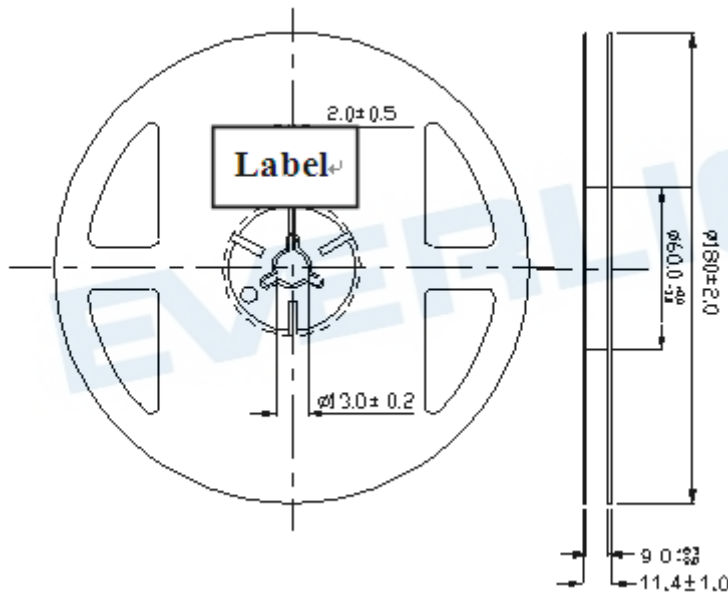
RoHS Pb **EVERLIGHT** 5

CPN: XXXXXXXXXXXXXXXXXXXX
 XXXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX
 P/N: XXXXXXXXXXXX
 XXXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX
 LOT NO: Y150716XXX-XXXXXXXXXX-XXXXXXXXXX
 QTY: 0123456789 HUE: XXXXXXXXXXXX
 CAT: XXXXXXXXXXXX REF: XXXXXXXXXXXX
 REFERENCE: BTPYYMDDXXXXX
 MSL-X MADE IN XXXXXX



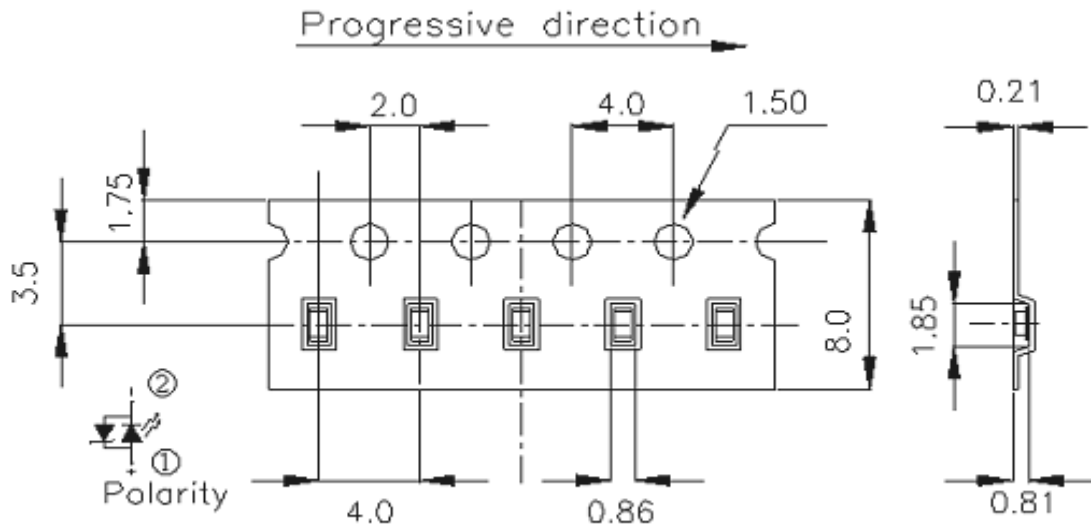
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

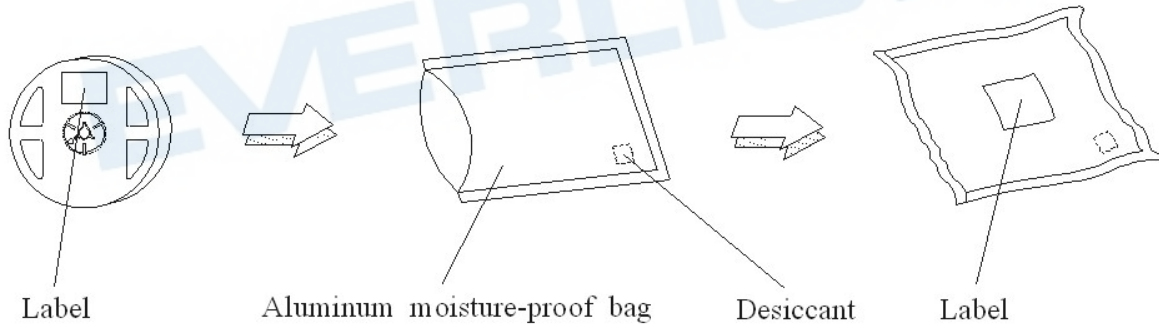
Carrier Tape Dimensions: Loaded Quantity 3000 pcs Per Reel



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

Moisture Resistant Packing Process

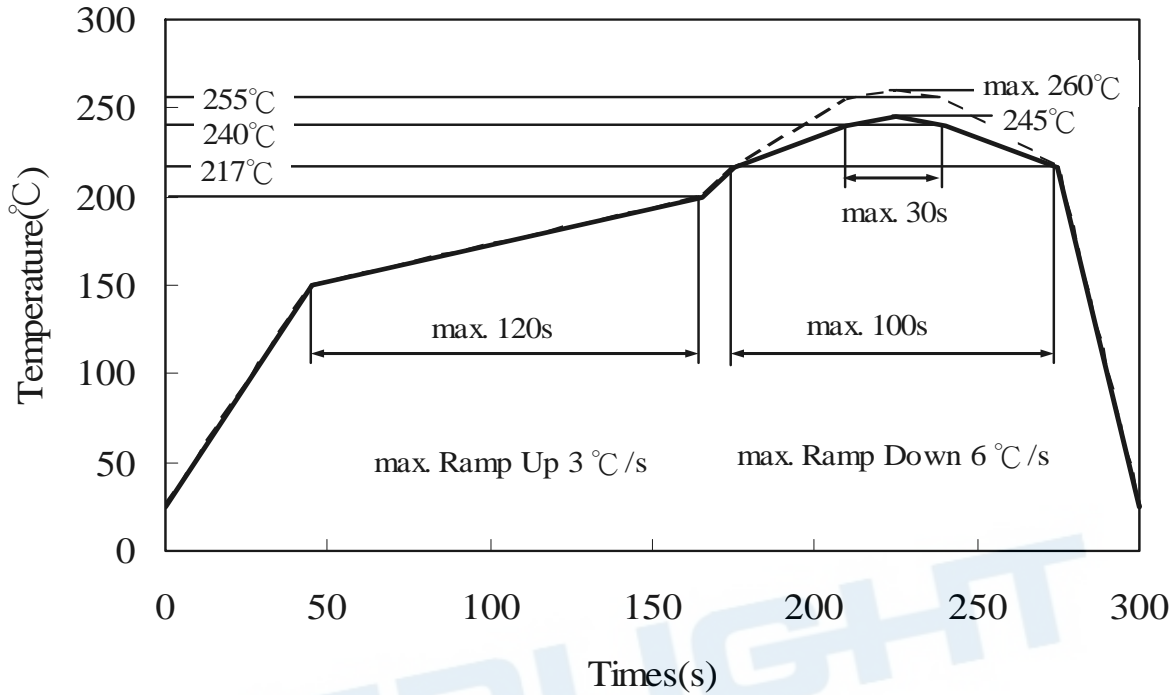


Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

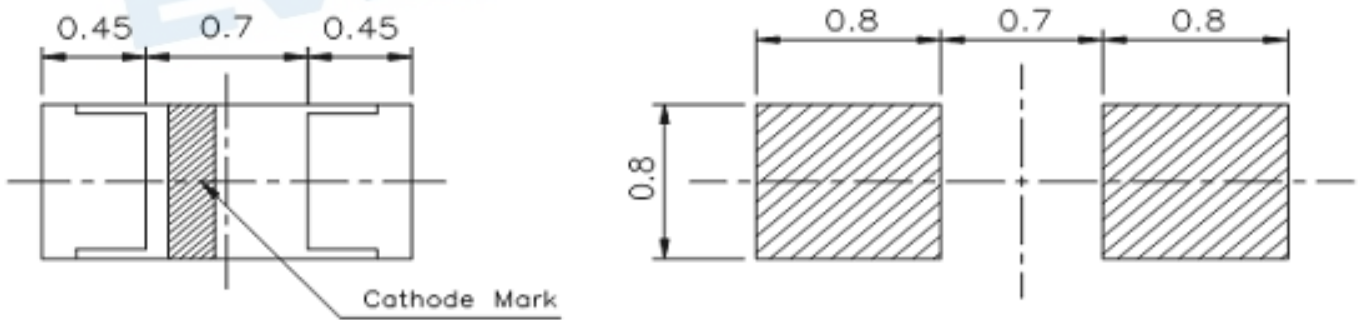
Precautions for Use

1. Soldering Condition (Reference: IPC/JEDEC J-STD-020D)

a. IR reflow



(B) Recommend soldering pad



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

3.1 Moisture proof bag should only be opened immediately prior to usage.

3.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.

3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.

3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350°C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.

Application Restrictions

1. High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

Revision History:

Rev.	Modified date	File modified contents
1	2010/5/25	New Spec
2	2013/9/27	Really Released
3	2023/7/4	Remove the VR&IR logo